CLAIMS

I claim:

- 1 1. A system comprising:
- 2 a case;
- 3 a component mounted on the case; and
- 4 a string positioned between the component and the case, the string
- 5 comprising a longitudinal element and a plurality of conductive filaments
- 6 transversely mounted on the longitudinal element.
- 1 2. The system of claim 1 wherein at least a portion of the plurality
- 2 of the conductive filaments of the string contact the case and the
- 3 component.
- 1 3. The system of claim 1 wherein the case defines an interior, an
- 2 opening being formed in the case between the interior of the case and an
- exterior of the case. 3
- 1 4. The system of claim 3 wherein the component is positioned
- 2 adjacent to the opening in the case, and the string is positioned adjacent
- 3 to the opening.
- 5. The system of claim 3 wherein the opening has a perimeter with 1
- 2 a length, the string being positioned adjacent to at least a portion of the
- 3 length of the perimeter of the opening.
- 6. The system of claim 3 wherein the perimeter of the opening is 1
- 2 substantially rectangular with sides, the string being positioned adjacent
- 3 to at least one of the sides of the perimeter of the opening in the case.
- 1 7. The system of claim 1 wherein the component comprises a power
- 2 supply.
- 1 8. The system of claim 1 wherein the component comprises a drive. - 15 -

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- 9. The system of claim 3 wherein the component is located in the interior of the case.
- 1 10. The system of claim 1 wherein the component is removably mounted on the case.
- 1 11. The system of claim 10 wherein the case is configured so that
 2 the component is removable through the opening in the case.
- 1 12. The system of claim 10 wherein the case configured so that the component is positionable adjacent to the opening in the case from the interior of the case.
- 1 13. The system of claim 1 wherein the component generates 2 radiation when operating.

- 1 14. A method of reducing radiation from a case housing at least one 2 electronic component and having an opening formed therein with a 3 perimeter, the method comprising:
- positioning a string having transverse conductive filaments along at least a portion of the perimeter of the opening; and
- installing the electronic component adjacent to the opening in the
 case with the string being positioned between the component and the case
 adjacent to the perimeter of the opening.
- 1 15. The method of claim 14 wherein the step of installing the component is performed after the step of positioning the string.
- 1 16. The method of claim 14 wherein the step of installing the component comprises inserting the component through the opening in the case.